

**Listing of Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-6 (canceled).

7. (Previously Presented) An integrated circuit package, comprising:  
a lead frame assembly, including:

a central support member having opposing first and second major surfaces; and

a plurality of conductive leads radially disposed about the periphery of the central support member;

an integrated circuit die coupled to the first surface and having a plurality of bond pads;

a plurality of wire bonds each coupling one of the plurality of bond pads and one of the plurality of conductive leads; and

a power cell coupled to the second surface.

8. (Previously Presented) The package recited in Claim 7 wherein the power cell includes:

an anode layer;

a cathode layer; and

a separator layer interposing the anode and cathode layers.

9. (Original) The package recited in Claim 8 wherein the cathode layer includes manganese dioxide, the separator layer includes lithium perchlorate and the anode layer includes lithium foil.

10. (Previously Presented) The package recited in Claim 7 further comprising:  
a power cell wire bond having a first terminus coupled to one of the plurality of bond pads; and  
an electrode, including:  
a planar body coupled to the power cell opposite the central support member; and  
a terminal coupled to the body and configured to position a second terminus of the power cell wire bond in a reference plane that is substantially coincident with the first surface, wherein the terminal is integral to the body.
11. (Previously Presented) The package recited in Claim 10 further comprising an insulating layer substantially covering surfaces of the body and the terminal that are opposite the power cell.
12. (Original) The package recited in Claim 11 wherein the insulating layer comprises a paper material.
13. (Original) The package recited in Claim 11 wherein the insulating layer comprises a polyester film material.
14. (Previously Presented) The package recited in Claim 10 wherein the body and the terminal each comprise copper.
15. (Previously Presented) The package recited in Claim 10 wherein the body and the terminal each comprise copper and nickel.
16. (Previously Presented) The package recited in Claim 10 further comprising a coating of electrical conduction enhancement material on at least one surface of the electrode.

17. (Original) The package recited in Claim 16 wherein the electrical conduction enhancement material is a graphite based, air-curable material.

18. (Original) The package recited in Claim 16 wherein the electrical conduction enhancement material is a graphite based, heat-curable material.

19. (Canceled).

20. (Canceled).

21. (Previously Presented) An integrated circuit package, comprising:  
an electrode having a substantially planar body and a terminal extending from the body;  
an integrated circuit die;  
a wire bond having a first end coupled to the integrated circuit die and a second end coupled to the electrode terminal; and  
a power cell interposing the electrode body and the integrated circuit die and coupled directly to at least one of the integrated circuit die and the electrode body;  
wherein the electrode terminal is configured to position the second wire bond end at a perpendicular distance from the body.

22. (Previously Presented) The integrated circuit package recited in Claim 21 wherein the electrode body has a first thickness and the power cell has a second thickness, and wherein the perpendicular distance is not substantially less than the sum of the first and second thicknesses.

23. (Previously Presented) The integrated circuit package recited in Claim 21 wherein the body, power cell and integrated circuit die have substantially similar footprints.

24. (Previously Presented) The integrated circuit package recited in Claim 21 wherein:  
the integrated circuit die includes one of an n-type semiconductor device substrate and a p-type semiconductor device substrate;  
the power cell is a solid state power cell having a cathode layer, an anode layer, and a separator layer interposing the cathode and anode layers;  
the anode interposes the cathode and the integrated circuit die when the integrated circuit die includes the n-type semiconductor device substrate; and  
the cathode interposes the anode and the integrated circuit die when the integrated circuit die includes the p-type semiconductor device substrate.

25. (Previously Presented) The integrated circuit package recited in Claim 21 wherein the electrode body includes a coating of electrical conduction enhancing material, and wherein the power cell is coupled directly to the coating.

26. (Previously Presented) The integrated circuit package recited in Claim 21 wherein the electrode body and the electrode terminal each comprise at least one of copper and nickel.

27. (Previously Presented) An integrated circuit package, comprising:

- a lead frame assembly having a central support member (CSM), the CSM having opposing first and second CSM surfaces;
- an integrated circuit die (ICD) having opposing first and second ICD surfaces, wherein the first ICD surface is coupled directly to the first CSM surface;
- a laminated, solid state power cell having a cathode layer, an anode layer, and a separator layer interposing the cathode and anode layers, wherein a first one of the cathode and anode layers is coupled directly to the second CSM surface;
- an electrode having a substantially planar body and a terminal extending from the body, wherein the electrode body is coupled directly to a second one of the cathode and anode layers of the power cell; and
- a wire bond having first and second ends, wherein the first end is coupled directly to the second ICD surface, and wherein the second end is coupled directly to the electrode terminal proximate one of the first and second CSM surfaces.

28. (Previously Presented) The integrated circuit package of Claim 27 wherein the ICD, the power cell and the electrode body having substantially similar footprints.